# onsemi

Final Product/Process Change Notification Document #:FPCN24821X Issue Date:03 Nov 2022

| Title of Change:                             | NCP12400 Family design change for improved yields   |  |  |  |  |
|--|---|--|--|--|--|
| Proposed First Ship date:                    | 08 Feb 2023 or earlier i  | 08 Feb 2023 or earlier if approved by customer |  |  |  |
| Contact Information:                         | Contact your local onsemi Sales Office or Scott.Brow@onsemi.com   |  |  |  |  |
| PCN Samples Contact:                         | Contact your local onsemi Sales Office.<br>Sample requests are to be submitted no later than 30 days from the date of first notification,<br>Initial PCN or Final PCN, for this change.<br>Samples delivery timing will be subject to request date, sample quantity and special customer<br>packing/label requirements. |  |  |  |  |
| Additional Reliability Data:                 | Contact your local onsemi Sales Office or Tomas.Vajter@onsemi.com   |  |  |  |  |
| Type of Notification:                        | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.<br>onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com    |  |  |  |  |
| Marking of Parts/ Traceability of<br>Change: | Product with the designated change can be identified by lot and date code information.  |  |  |  |  |
| Change Category:                             | Wafer Fab Change  |  |  |  |  |
| Change Sub-Category(s):                      | Datasheet/Product Doc change, Design Change   |  |  |  |  |
| Sites Affected:                              |   |  |  |  |  |
| onsemi Sites                                 |   | External Foundry/Subcon Sites                  |  |  |  |
| onsemi, Gresham United States                |   | None   |  |  |  |

#### **Description and Purpose:**

onsemi would like to inform its customers of a design change to the NCP12400 family of products which are listed in the List of Affected Parts below. These design changes are intended to improve the overall yield of the product and stabilize our ability to effectively provide product to our customers. While there are some datasheet changes associated with this that were unavoidable, the product is expected to be a drop-in replacement to the existing design. Customers are highly recommended to request samples to validate any changes. We will not be able to accept any rejections of the FPCN when it is released, as we will not be able to maintain the original product and have to convert to the new design.

|                   | From              | То                             |
|-------------------|-------------------|--------------------------------|
| Data sheet        | Rev 8             | Rev 9                          |
| Parametric Change | Current Datasheet | See Parametric changes summary |

As the product is qualified for assembly at both onsemi Carmona, Philippines and ATXKS, reliability data was taken at both sites for this change.

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.



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| Characteristic  |  | Test Condition   | Sym   | bol  |  | Before                     | :          |  | Aft                   | er  |   |
|---|--|--|---|--|--|----------------------------|------------|--|-----------------------|---|---|
| Brown-Out thre  | esholds (option BAHAB)   | V <sub>HV</sub> going up                                       | VHV(star  | -  | 93   | 103                        | 113        | 93                                     | 103                   | 113   | v   |
| brown out thresholds (option barrab)  |  | V <sub>HV</sub> going down                                     | VHV(stop  |  | 90   | 100                        | 110        | 87                                     | 97                    | 107   | -   |
| Brown-Out thresholds (option C)   |  | V <sub>HV</sub> going up<br>V <sub>HV</sub> going down         | VHV(star<br>VHV(stop  | -  | 87<br>85   | 95<br>93                   | 103<br>101 | 87<br><mark>82</mark>                  | 95<br><mark>90</mark> | 103<br><mark>98</mark>                            | V   |
| Timer duration  | for no line detection  |  | tX2_DET   |  | 21   | 32                         | 43         | 70                                     | 100                   | 130   | ms  |
| HV pin voltage<br>ended   | when X2 discharging process is   |  | VX2_END   | )  | 10   | 11                         | 12         | 20                                     | 30                    | 40  | v   |
| X2 Discharge cu   | ge for current source operation  |  |   | IDISCH   |  | 2                          | 3          |  | 4                     | mA  |   |
| Reliability Dat   | a Summary:<br>ME NCP12400CBBAB0DR2G  |  |   | •  |  |                            |            |  |                       |   |   |
| QV DEVICE NA<br>RMS 80799 OS  | ME NCP12400CBBAB0DR2G  |  | Condi   | tion   |  |                            |            | Interva                                | al                    | Res   | ults  |
| QV DEVICE NA<br>RMS 80799 OS<br>PACKAGE SOIC  | ME NCP12400CBBAB0DR2G<br>SPI<br>C 8-P7 STD VHVIC PBFH  | Ta=125°C, :  |   |  | :, HV=   | 800V                       |            | Interva<br>1008 h                      |                       |   | ults<br>80  |
| QV DEVICE NA<br>RMS 80799 OS<br>PACKAGE SOIC<br>Test  | ME NCP12400CBBAB0DR2G<br>SPI<br>C 8-P7 STD VHVIC PBFH<br>Specification   | Ta=125°C, 1  |   | rated Vcc  | :, HV=   | 800V                       |            |  | rs                    | 0/  |   |
| QV DEVICE NA<br>RMS 80799 OS<br>PACKAGE SOIC<br>Test<br>HTOL  | ME NCP12400CBBAB0DR2G<br>SPI<br>2 8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108  | Ta=125°C, :<br>MSL 1 @ 260 °                                   | 100 % max<br>Ta=15  | rated Vcc<br>50°C<br>JHAST, HA   |  |                            | 2          | 1008 hi                                | rs                    | 0/<br>0/3   | 80  |
| QV DEVICE NA<br>RMS 80799 OS<br>PACKAGE SOIC<br>Test<br>HTOL<br>HTSL                                    | ME NCP12400CBBAB0DR2G<br>SPI<br>2 8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103   | MSL 1 @ 260 °  | 100 % max<br>Ta=15<br>C, Pre TC, ι  | rated Vcc<br>50°C<br>1HAST, HA<br>(gs only   |  |                            | 2          | 1008 hi                                | rs<br>rs              | 0/<br>0/3   | 80<br>320<br>200                                    |
| AV DEVICE NA<br>MS 80799 OS<br>ACKAGE SOIC<br>Test<br>HTOL<br>HTSL<br>PC<br>TC<br>HAST                  | ME NCP12400CBBAB0DR2G<br>SPI<br>2 8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103<br>J-STD-020 JESD-A113<br>JESD22-A104<br>JESD22-A110  | MSL 1 @ 260 °  | 100 % max<br>Ta=15<br>C, Pre TC, u<br>mount pk<br>Ta= -65°C t<br>C, 85% RH,   | rated Vcc<br>50°C<br>JHAST, HA<br>(gs only<br>to +150°C<br>18.8psig,   | AST fo<br>bias                                       | r surface                  |            | 1008 hi<br>2016 hi<br>500 cy<br>192 hr | rs<br>rs<br>c<br>s    | 0/<br>0/3<br>0/1<br>0/3<br>0/3                    | 80<br>320<br>200<br>320<br>320                      |
| AV DEVICE NA<br>MS 80799 OS<br>ACKAGE SOIC<br>Test<br>HTOL<br>HTSL<br>PC<br>TC<br>HAST<br>UHAST         | ME NCP12400CBBAB0DR2G<br>SPI<br>2.8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103<br>J-STD-020 JESD-A113<br>JESD22-A104<br>JESD22-A110<br>JESD22-A118   | MSL 1 @ 260 °<br>130°C,<br>130°C,                              | 100 % max<br>Ta=15<br>C, Pre TC, u<br>mount pl<br>Ta= -65°C t<br>C, 85% RH, 18  | rated Vcc<br>50°C<br>JHAST, HA<br>(gs only<br>o +150°C<br>18.8psig, un   | AST fo<br>bias                                       | r surface                  | 2          | 1008 hi<br>2016 hi<br>500 cy           | rs<br>rs<br>c<br>s    | 0/<br>0/3<br>0/1<br>0/3<br>0/3                    | 80<br>320<br>200<br>320                             |
| QV DEVICE NA<br>MS 80799 OS<br>PACKAGE SOIC<br>Test<br>HTOL<br>HTSL<br>PC<br>TC<br>HAST                 | ME NCP12400CBBAB0DR2G<br>SPI<br>2 8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103<br>J-STD-020 JESD-A113<br>JESD22-A104<br>JESD22-A110  | MSL 1 @ 260 °<br>130°<br>130°C, 5<br>Cpk 1                     | 100 % max<br>Ta=15<br>C, Pre TC, u<br>mount pl<br>Ta= -65°C t<br>C, 85% RH,<br>85% RH, 18<br>.33, 30 bor                | rated Vcc<br>50°C<br>HAST, HA<br>(gs only<br>o +150°C<br>18.8psig, un<br>ds from 5                                       | AST fo<br>bias<br>biase<br>bunits                    | r surface                  |            | 1008 hi<br>2016 hi<br>500 cy<br>192 hr | rs<br>rs<br>c<br>s    | 0/3<br>0/3<br>0/1<br>0/3<br>0/3                   | 80<br>320<br>200<br>320<br>320                      |
| AV DEVICE NA<br>AMS 80799 OS<br>PACKAGE SOIC<br>Test<br>HTOL<br>HTSL<br>PC<br>TC<br>HAST<br>UHAST       | ME NCP12400CBBAB0DR2G<br>PI<br>2 8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103<br>J-STD-020 JESD-A113<br>JESD22-A104<br>JESD22-A104<br>JESD22-A110<br>JESD22-A118<br>AEC-Q100-001<br>AEC-Q100-001 | MSL 1 @ 260 °<br>130°C,<br>130°C,                              | 100 % max<br>Ta=15<br>C, Pre TC, u<br>mount pl<br>Ta= -65°C t<br>C, 85% RH,<br>85% RH, 18<br>.33, 30 bor                | rated Vcc<br>50°C<br>HAST, HA<br>(gs only<br>0 +150°C<br>18.8psig, un<br>ds from 5<br>units, After                       | AST fo<br>bias<br>biase<br>bunits                    | r surface                  |            | 1008 hi<br>2016 hi<br>500 cy<br>192 hr | rs<br>rs<br>c<br>s    | 0/<br>0/3<br>0/1<br>0/3<br>0/3<br>0/3             | 80<br>320<br>200<br>320<br>320<br>320               |
| QV DEVICE NA<br>RMS 80799 OS<br>PACKAGE SOIC<br>Test<br>HTOL<br>HTSL<br>PC<br>TC<br>HAST<br>UHAST<br>BS | ME NCP12400CBBAB0DR2G<br>SPI<br>2.8-P7 STD VHVIC PBFH<br>Specification<br>JESD22-A108<br>JESD22-A103<br>J-STD-020 JESD-A113<br>JESD22-A104<br>JESD22-A100<br>JESD22-A110<br>JESD22-A118<br>AEC-Q100-001                | MSL 1 @ 260 °<br>130°<br>130°C, 1<br>Cpk 1<br>Cpk 1.33, 30 bor | 100 % max<br>Ta=15<br>C, Pre TC, u<br>mount pl<br>Ta= -65°C t<br>C, 85% RH,<br>85% RH, 18<br>.33, 30 bor<br>nds from 5u | rated Vcc<br>50°C<br>HAST, HA<br>kgs only<br>o +150°C<br>18.8psig, un<br>ds from 5<br>Inits, After<br>8/2016<br>orce Min | AST fo<br>bias<br>biase<br>biase<br>bianits<br>r TC5 | r surface<br>ed<br>00/1000 |            | 1008 hi<br>2016 hi<br>500 cy<br>192 hr | rs<br>rs<br>c<br>s    | 0/<br>0/3<br>0/1<br>0/3<br>0/3<br>0/3<br>pa<br>pa | 80<br>320<br>200<br>320<br>320<br>320<br>320<br>320 |

|         | Method 2011  |                              |                        |      |
|---------|--|------------------------------|------------------------|------|
| DDC     | BPS M883 3gm Pull Force Min After TC500/1000 &   Method 2011 HTSL1008/2016 |                              |                        | pass |
| BF3     |  |                              |                        | pass |
| ESD HBM | AEC-Q100-002   | c = 0, Test @ R, HV included | 2.5kV                  | 0/3  |
| ESD HBM | AEC-Q100-002   | c = 0, Test @ R, HV excluded | 5kV                    | 0/3  |
| ESD CDM | AEC-Q100-011   | c = 0, Test @ R              | 1.25kV                 | 0/3  |
| ED      | ON Data Sheet  | Cpk > 1.67<br>Test @ R, H, C | Cpk>1.67               | 0/90 |
| LU      | AEC-Q100-004   | Test @ EP; Test & Stress @ R | LU+>100mA<br>LU->100mA | 0/6  |



#### QV DEVICE NAME NCP12400CBBAB0DR2G RMS 82290 ATXKS PACKAGE SOIC 8-P7 STD VHVIC PBFH

| Test  | Specification       | Condition  | Interval | Results |
|-------|---------------------|--|----------|---------|
| HTOL  | JESD22-A108         | Ta=125°C, 100 % max rated Vcc, HV=800V                             | 1008 hrs | 0/80    |
| HTSL  | JESD22-A103         | Ta=150°C   | 1008 hrs | 0/80    |
| PC    | J-STD-020 JESD-A113 | MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface<br>mount pkgs only |          | 0/330   |
| TC    | JESD22-A104         | Ta= -65°C to +150°C  | 500 cyc  | 0/80    |
| HAST  | JESD22-A110         | 130°C, 85% RH, 18.8psig, bias                                      | 192 hrs  | 0/80    |
| uHAST | JESD22-A118         | 130°C, 85% RH, 18.8psig, unbiased                                  | 96 hrs   | 0/80    |
| BPS   | M883<br>Method 2011 | 3gm Pull Force Min   |          | pass    |
| BPS   | M883<br>Method 2011 | 3gm Pull Force Min After TC500                                     |          | pass    |
| ED    | ON Data Sheet       | Cpk > 1.67<br>Test @ R, H, C                                       | Cpk>1.67 | 0/30    |

#### **Electrical Characteristics Summary:**

Parametric changes summary above.

#### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Part Number        | Qualification Vehicle |
|--------------------|-----------------------|
| NCP12400BBAAA0DR2G | NCP12400CBBAB0DR2G    |
| NCP12401EBEAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12401CBEAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400BBHAA1DR2G | NCP12400CBBAB0DR2G    |
| NCP12400BBHAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400CAHAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400CBAAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400CBBAB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400CBHAA0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400EAHBB0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400BBEBA0DR2G | NCP12400CBBAB0DR2G    |
| NCP12400BBBBB2DR2G | NCP12400CBBAB0DR2G    |
| NCP12400BBBBA0DR2G | NCP12400CBBAB0DR2G    |

## Appendix A: Changed Products

### DIKG: DIGI-KEY

| Product            | Customer Part Number | Qualification Vehicle | New Part Number | Replacement Supplier |
|--------------------|----------------------|-----------------------|-----------------|----------------------|
| NCP12400CBAAB0DR2G |                      | NCP12400CBBAB0DR2G    |                 |                      |
| NCP12400CBBAB0DR2G |                      | NCP12400CBBAB0DR2G    |                 |                      |
| NCP12400EAHBB0DR2G |                      | NCP12400CBBAB0DR2G    |                 |                      |
| NCP12400BBEBA0DR2G |                      | NCP12400CBBAB0DR2G    |                 |                      |